DESCRIPTION
The MeshConnect™ EM357 Mini Modules from California Eastern Laboratories (CEL) combine high performance RF solutions with the market's premier ZigBee® stack. Available in low and high output power options (+8dBm and +20dBm), these modules can accommodate variable range and performance requirements. The mini module footprint makes them suitable for a wide range of ZigBee applications. The MeshConnect EM357 Mini Modules are certified and qualified, enabling customers to accelerate time to market by greatly reducing the design and certification phases of development.

CEL's MeshConnect EM357 Mini Modules (ZICM357SP0 and ZICM357SP2) are based on the Ember EM357 ZigBee compliant SoC radio IC. The IC is a single-chip solution, compliant with ZigBee specifications and IEEE 802.15.4, a complete wireless solution for all ZigBee applications. The IC consists of an RF transceiver with the baseband modem, a hardwired MAC and an embedded 32-bit ARM® Cortex™-M3 microcontroller with internal RAM (12kB) and Flash (192kB) memory. The device provides numerous general-purpose I/O pins and peripheral functions such as timers and UARTs.

FEATURES
- High RF Performance:
  - Up to 123dB RF Link Budget
  - RX Sensitivity: -100dBm (ZICM357SP0) -103dBm (ZICM357SP2)
- Data Rate: 250kbps
- Advanced Cortex-M3 Processor
- Advanced Power Management
- 16 RF Channels
- Industry’s Premier ZigBee Pro Stack: EmberZNet PRO™
- Mini Footprint: 0.940” x 0.655” (23.9mm x 16.6mm)
- Antenna Options
  1) Integrated PCB Trace Antenna
  2) RF Port for External Antenna
- Supports Mesh Networks
- AES Encryption
- FCC, CE and IC Certifications
- ROHS Compliant

APLICATIONS
- Smart Energy/Grid Markets
  - Thermostats
  - In-Home Displays
  - Smart Plugs
- Home Automation and Control
  - Energy Management
  - Security Devices
  - HVAC Control
- Building Automation and Control
- Commercial and Residential Lighting
- Fixtures and Control
- Solar Inverters and Control
- General ZigBee Wireless Sensor Networking
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ORDERING INFORMATION

<table>
<thead>
<tr>
<th>Part Number</th>
<th>Order Number</th>
<th>Description</th>
<th>Min/Multiple</th>
</tr>
</thead>
<tbody>
<tr>
<td>ZICM357SP0-1</td>
<td>330/330</td>
<td>+8dBm Output Power, PCB Trace antenna; tray package</td>
<td></td>
</tr>
<tr>
<td>ZICM357SP0-1-R</td>
<td>600/600</td>
<td>+8dBm Output Power, PCB Trace antenna; tape and reel package</td>
<td></td>
</tr>
<tr>
<td>ZICM357SP0-1C</td>
<td>330/330</td>
<td>+8dBm Output Power, with Castellation pin for external antenna; tray package</td>
<td></td>
</tr>
<tr>
<td>ZICM357SP0-1C-R</td>
<td>600/600</td>
<td>+8dBm Output Power, with Castellation pin for external antenna; tape and reel package</td>
<td></td>
</tr>
<tr>
<td>ZICM357SP2-1</td>
<td>330/330</td>
<td>+20dBm Output Power, PCB Trace antenna; tray package</td>
<td></td>
</tr>
<tr>
<td>ZICM357SP2-1-R</td>
<td>600/600</td>
<td>+20dBm Output Power, PCB Trace antenna; tape and reel package</td>
<td></td>
</tr>
<tr>
<td>ZICM357SP2-1C</td>
<td>330/330</td>
<td>+20dBm Output Power, with Castellation pin for external antenna; tray package</td>
<td></td>
</tr>
<tr>
<td>ZICM357SP2-1C-R</td>
<td>600/600</td>
<td>+20dBm Output Power, with Castellation pin for external antenna; tape and reel package</td>
<td></td>
</tr>
<tr>
<td>ZICM-EM35X-DEV-KIT</td>
<td>1/1</td>
<td>MeshConnect EM35x Ember Companion Kit for Ember EM35x Development Kit (See below for kit content and details)</td>
<td></td>
</tr>
</tbody>
</table>

Note: All packages come in Trays unless a part number has a "-R" designation; part numbers with the "-R" indicate a Tape and Reel Package Option.

MODULE BLOCK DIAGRAMS

DEVELOPMENT TOOLS

Ember Companion Kit:
CEL's MeshConnect EM35x Ember Companion Kit is designed to work with the Ember development kit (EM35X-DEV and EM35X-DEV-IAR). Each module in this CEL kit is soldered on a carrier board making it pin-for-pin compatible with the Ember Development Board.

For more information regarding the MeshConnect Development Kit, refer to the respective Development Kit User Guides documents, or visit www.cel.com/MeshConnect.

EM35x Ember Companion Kit

Kit Contents:
- ZICM357SP2-1 Modules (2)
- ZICM357SP2-1C Module (1)
- ZICM357SP0-1 Modules (2)
- ZICM357SP0-1C Module (1)
- Online Documentation
TRANSCEIVER IC
CEL’s MeshConnect EM357 Mini Modules use the Ember EM357 transceiver IC. This IC incorporates the RF transceiver with the baseband modem, a hardwired MAC, and an embedded ARM® Cortex™-M3 microcontroller, offering an excellent low cost high performance solution for all IEEE 802.15.4 / ZigBee applications. For more information about the EM357 IC, visit www.silabs.com.

ANTENNA
CEL’s MeshConnect EM357 Mini Modules include an integrated Printed Circuit Board (PCB) trace antenna. An optional configuration which uses a castellation pin on the module allows the user to connect an external antenna. The ZICM357SP0 has been certified with the PCB trace antenna only while the ZICM357SP2 has been certified with the PCB trace antenna and a Nearson half-wave dipole antenna (part number: S181AH-2450S) on a 4 inch cable using the castellation pin of the module. Please refer to the document ZICM357SP2-1C External Antenna Implementation for details describing the requirements that must be followed to take advantage of the CEL certification.

The PCB antenna employs a topology that is compact and highly efficient. To maximize range, an adequate ground plane must be provided on the host PCB. Correctly positioned, the ground plane on the host PCB will contribute significantly to the antenna performance (it should not be directly under the module PCB Antenna). The position of the module on the host board and overall design of the product enclosure contribute to antenna performance. Poor design affects radiation patterns and can result in reflection, diffraction and/or scattering of the transmitted signal.

For optimum antenna performance, the MeshConnect Modules should be mounted with the PCB trace antenna overhanging the edge of the host board. To further improve performance, a ground plane should be placed on the host board under the module, up to the antenna (a minimum of 1.5” x 1.5” is recommended). The installation of an uninterrupted ground plane on a layer directly beneath the module will also allow you to run traces under this layer. CEL can provide assistance with your PCB layout.

The following are some design guidelines to help ensure antenna performance:

- Never place the ground plane or route copper traces directly underneath the antenna portion of the module
- Never place the antenna close to metallic objects
- In the overall design, ensure that wiring and other components are not placed near the antenna
- Do not place the antenna in a metallic or metalized plastic enclosure
- Keep plastic enclosures 1 cm or more away from the antenna in any direction

Under Industry Canada regulations, this radio transmitter may only operate using an antenna of a type and maximum (or lesser) gain approved for the transmitter by Industry Canada. To reduce potential radio interference to other users, the antenna type and its gain should be so chosen that the equivalent isotropically radiated power (e.i.r.p.) is not more than that necessary for successful communication.

Conformément à la réglementation d’Industrie Canada, le présent émetteur radio peut fonctionner avec une antenne d’un type et d’un gain maximal (ou inférieur) approuvé pour l’émetteur par Industrie Canada. Dans le but de réduire les risques de brouillage radioélectrique à l’intention des autres utilisateurs, il faut choisir le type d’antenne et son gain de sorte que la puissance isotope rayonnée équivalente (p.i.r.e.) ne dépasse pas l’intensité nécessaire à l’établissement d’une communication satisfaisante.

POWER AMPLIFIER
CEL’s MeshConnect EM357 High Power Module (ZICM357SP2) includes a Power Amplifier (PA). This PA delivers high efficiency, high gain, and high output power ($P_{\text{out}} = +20.0\text{dBm TYP}$) to provide an extended range and reliable transmission for fewer nodes in a network. For the ZICM357SP2, Power Mode 2 with Power Setting -2 is the maximum setting allowed for FCC compliance. Operating in Power Mode 3 at higher power settings may damage the PA.
SOFTWARE/FIRMWARE

CEL's MeshConnect EM357 Mini Modules are ideal platforms for EmberZNet PRO™, the industry’s most deployed and field proven ZigBee compliant stack supporting the ZigBee PRO feature Set. EmberNet PRO is a complete ZigBee protocol software package containing all the elements required for mesh networking applications. For more information regarding the software development for this IC, visit [www.silabs.com](http://www.silabs.com).

CEL provides reference software that runs multiple functions and executes various commands. The firmware allows the execution of IEEE 802.15.4 communication, validation and manufacturing tests. For example, users can setup a simple ZigBee Point-to-Point network to perform Range and Packet Error Rate (PER) tests. The software can also place the module in various operating modes, which allows for setting and/or testing various parameters.

The ZICM357SP0 uses the transceiver's Primary RF ports for transmitting and should use Power Mode 1. The ZICM357SP2 uses the transceiver's Alternate RF ports for transmitting and should use Power Mode 2.
### ABSOLUTE MAXIMUM RATINGS

<table>
<thead>
<tr>
<th>Description</th>
<th>MeshConnect ZICM357SPx Module</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>Power Supply Voltage (V(\text{DD}))</td>
<td>-0.3</td>
<td>3.6</td>
</tr>
<tr>
<td>Voltage on any I/O Line</td>
<td>-0.3</td>
<td>V(\text{DD}) + 0.3</td>
</tr>
<tr>
<td>RF Input Power</td>
<td>ZICM357SP0</td>
<td>+15</td>
</tr>
<tr>
<td></td>
<td>ZICM357SP2</td>
<td>+5</td>
</tr>
<tr>
<td>Storage Temperature Range</td>
<td>-40</td>
<td>125</td>
</tr>
<tr>
<td>Reflow Soldering Temperature</td>
<td>-20</td>
<td>260</td>
</tr>
</tbody>
</table>

*Note: Exceeding the maximum ratings may cause permanent damage to the module or devices.*

### RECOMMENDED (OPERATING CONDITIONS)

<table>
<thead>
<tr>
<th>Description</th>
<th>MeshConnect ZICM357SPx Module</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>Power Supply Voltage (V(\text{DD}))</td>
<td>2.1</td>
<td>3.6</td>
</tr>
<tr>
<td>Input Frequency</td>
<td>2405</td>
<td>2480</td>
</tr>
<tr>
<td>Ambient Temperature Range</td>
<td>-40</td>
<td>25</td>
</tr>
</tbody>
</table>

### DC CHARACTERISTICS (\(\text{@ 25}°\text{C, VDD = 3.3V, ZICM357SP0 TX Power Mode 1, ZICM357SP2 TX Power Mode 2}\))

<table>
<thead>
<tr>
<th>Description</th>
<th>MeshConnect ZICM357SPx Module</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>Transmit Mode Current @ 8dBm</td>
<td>ZICM357SP0</td>
<td>44</td>
</tr>
<tr>
<td>Transmit Mode Current @ 0dBm</td>
<td>ZICM357SP0</td>
<td>31</td>
</tr>
<tr>
<td>Receive Mode Current</td>
<td>ZICM357SP0</td>
<td>30</td>
</tr>
<tr>
<td>Transmit Mode Current @ 20dBm</td>
<td>ZICM357SP2</td>
<td>150</td>
</tr>
<tr>
<td>Transmit Mode Current @ 0dBm</td>
<td>ZICM357SP2</td>
<td>58</td>
</tr>
<tr>
<td>Receive Mode Current</td>
<td>ZICM357SP2</td>
<td>34</td>
</tr>
<tr>
<td>Sleep Mode Current</td>
<td>ZICM357SP2</td>
<td>1</td>
</tr>
</tbody>
</table>

### RF CHARACTERISTICS (\(\text{@ 25}°\text{C, VDD = 3.3V, ZICM357SP0 TX Power Mode 1, ZICM357SP2 TX Power Mode 2}\))

<table>
<thead>
<tr>
<th>Description</th>
<th>MeshConnect ZICM357SPx Module</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>RF Frequency Range</td>
<td>ZICM357SP0</td>
<td>2405</td>
</tr>
<tr>
<td>RF Channels</td>
<td>ZICM357SP0</td>
<td>11</td>
</tr>
<tr>
<td>Frequency Error Tolerance</td>
<td>ZICM357SP0</td>
<td>-96.2</td>
</tr>
<tr>
<td>Transmitter</td>
<td>ZICM357SP0</td>
<td>8</td>
</tr>
<tr>
<td>Minimum Output Power</td>
<td>ZICM357SP0</td>
<td>-40</td>
</tr>
<tr>
<td>Offset Error Vector Magnitude</td>
<td>ZICM357SP0</td>
<td>5</td>
</tr>
<tr>
<td>Maximum Output Power</td>
<td>ZICM357SP2</td>
<td>21</td>
</tr>
<tr>
<td>Minimum Output Power</td>
<td>ZICM357SP2</td>
<td>2</td>
</tr>
<tr>
<td>Offset Error Vector Magnitude</td>
<td>ZICM357SP2</td>
<td>5</td>
</tr>
<tr>
<td>Receiver</td>
<td>ZICM357SP0</td>
<td>-100</td>
</tr>
<tr>
<td>Saturation (maximum input level)</td>
<td>ZICM357SP0</td>
<td>0</td>
</tr>
<tr>
<td>Sensitivity (1% PER, boost mode)</td>
<td>ZICM357SP0</td>
<td>-103</td>
</tr>
<tr>
<td>Saturation (maximum input level)</td>
<td>ZICM357SP2</td>
<td>-10</td>
</tr>
</tbody>
</table>

*Note: For the ZICM357SP2 Module, Power Mode 2 with Power Setting -2 is the maximum setting allowed for FCC Compliance. Operating in Power Mode 3 at higher power settings may damage the PA.*
**PIN SIGNALS I/O PORT CONFIGURATION**

CEL’s MeshConnect Module has 33 edge I/O interfaces for connection to the user’s host board. The MeshConnect Module Dimensions shows the layout of the 33 edge castellations.

**MESHCONNECT I/O PIN ASSIGNMENTS**

<table>
<thead>
<tr>
<th>CEL MeshConnect ZICM357SPx Module Pin Number</th>
<th>Ember EM357 IC Pin Number</th>
<th>Name</th>
<th>Notes</th>
</tr>
</thead>
<tbody>
<tr>
<td>1, 2, 12, 31, 33</td>
<td>49</td>
<td>GROUND</td>
<td>Digital I/O TX_ACTIVE - Logic-level control for PA. The EM35x baseband controls TX_ACTIVE and drives it high when in TX mode. Applies only to the ZICM357SP0. PCS is a NC on the ZICM357SP2</td>
</tr>
<tr>
<td>3</td>
<td>11</td>
<td>PCS</td>
<td></td>
</tr>
<tr>
<td>4</td>
<td>12</td>
<td>RESET</td>
<td>Active Low chip reset (Input)</td>
</tr>
<tr>
<td>5</td>
<td>13</td>
<td>PC6</td>
<td>Digital I/O OSC32B - 32.768 kHz crystal oscillator nTX_ACTIVE - Inverted TX_ACTIVE signal</td>
</tr>
<tr>
<td>6</td>
<td>14</td>
<td>PC7</td>
<td>Digital I/O OSC32A - 32.768 kHz crystal oscillator OSC32_EXT - Digital 32.768 kHz clock input source</td>
</tr>
<tr>
<td>7</td>
<td>18</td>
<td>PA7</td>
<td>Digital I/O TIM1C4 - Timer 1 Channel 4 input/output REG_EN - External regulator open drain output</td>
</tr>
<tr>
<td>8</td>
<td>19</td>
<td>PB3</td>
<td>Digital I/O TIM2C3 - Timer 2 Channel 3 input/output SC1nCTS - UART CTS handshake of Serial Controller 1 SC1SCLK - SPI master/slave clock of Serial Controller 1</td>
</tr>
<tr>
<td>9</td>
<td>20</td>
<td>PB4</td>
<td>Digital I/O TIM2C4 - Timer 2 Channel 4 input/output SC1nRTS - UART RTS handshake of Serial Controller 1 SC1nSSEL - SPI slave select of Serial Controller 1</td>
</tr>
<tr>
<td>10</td>
<td>21</td>
<td>PA0</td>
<td>Digital I/O TIM2C1 - Timer 2 Channel 1 input/output SC2MOSI - SPI master data out/slave data in of Serial Controller 2</td>
</tr>
<tr>
<td>11</td>
<td>22</td>
<td>PA1</td>
<td>Digital I/O TIM2C3 - Timer 2 Channel 3 input/output SC2SDA - TWI data of Serial Controller 2 SC2MISO - SPI master data in/slave data out of Serial Controller 2</td>
</tr>
<tr>
<td>13</td>
<td>16, 23, 28, 37</td>
<td>Vcc</td>
<td></td>
</tr>
<tr>
<td>14</td>
<td>24</td>
<td>PA2</td>
<td>Digital I/O TIM2C4 - Timer 2 Channel 4 input/output SC2SCL - TWI clock of Serial Controller 2 SC2SCLK - SPI master/slave clock of Serial Controller 2</td>
</tr>
<tr>
<td>15</td>
<td>25</td>
<td>PA3</td>
<td>Digital I/O TIM2C2 - Timer 2 Channel 2 input/output SC2nSSEL - SPI slave select of Serial Controller 2 TRACECLK - Synchronous CPU trace clock</td>
</tr>
<tr>
<td>16</td>
<td>26</td>
<td>PA4</td>
<td>Digital I/O ADC4 - ADC Input 4 PTI_EN - Frame signal of Packet Trace Interface (PTI) TRACEDATA2 - Synchronous CPU trace data bit 2</td>
</tr>
<tr>
<td>17</td>
<td>27</td>
<td>PA5</td>
<td>Digital I/O ADC5 - ADC Input 5 PTI_DATA - Data signal of Packet Trace Interface (PTI) nBOOTMODE - Embedded serial bootloader activation out of reset TRACEDATA3 - Synchronous CPU trace data bit 3</td>
</tr>
<tr>
<td>18</td>
<td>29</td>
<td>PA6</td>
<td>Digital I/O TIM1C3 - Timer 1 Channel 3 input/output</td>
</tr>
</tbody>
</table>
### MESHCONNECT I/O PIN ASSIGNMENTS (Continued)

<table>
<thead>
<tr>
<th>CEL MeshConnect ZICM357SPx Module Pin Number</th>
<th>Ember EM357 IC Pin Number</th>
<th>Name</th>
<th>Notes</th>
</tr>
</thead>
</table>
| 19                                          | 30                        | PB1  | Digital I/O  
SC1MISO - SPI slave data out of Serial Controller 1  
SC1MOSI - SPI master data out of Serial Controller 1  
SC1SDA - TWI data of Serial Controller 1  
SC1TXD - UART transmit data of Serial Controller 1  
TIM2C1 - Timer 2 channel 1 input/output |
| 20                                          | 31                        | PB2  | Digital I/O  
SC1MISO - SPI master data in of Serial Controller 1  
SC1MOSI - SPI slave data in of Serial Controller 1  
SC1SCL - TWI clock of Serial Controller 1  
SC1RXD - UART receive data of Serial Controller 1  
TIM2C2 - Timer 2 channel 2 input/output |
| 21                                          | 32                        | JTCK | JTAG clock input from debugger  
SWCLK - Serial Wire clock input/output with debugger |
| 22                                          | 33                        | PC2  | Digital I/O  
JTD0 - JTAG data out to debugger  
SWO - Serial Wire Output asynchronous trace output to debugger |
| 23                                          | 34                        | PC3  | Digital I/O  
JTD1 - JTAG data in from debugger |
| 24                                          | 35                        | PC4  | Digital I/O  
JTIMS - JTAG mode select from debugger  
SWDIO - Serial Wire bidirectional data to/from debugger |
| 25                                          | 36                        | PB0  | Digital I/O  
VREF - ADC reference input/output  
IRQA - External interrupt source A  
TRACECLK - Synchronous CPU trace clock  
TIM1CLK - Timer 1 external clock input  
TIM2MSK - Timer 2 external clock mask input |
| 26                                          | 38                        | PC1  | Digital I/O  
ADC3 - ADC Input 3  
SWO - Serial Wire Output asynchronous trace output to debugger  
TRACEDATA0 - Synchronous CPU trace data bit 0 |
| 27                                          | 40                        | PC0  | Digital I/O  
JIRST - JTAG reset input from debugger  
IRQD - Default external interrupt source D  
TRACEDATA1 - Synchronous CPU trace data bit 1 |
| 28                                          | 41                        | PB7  | Digital I/O  
ADC2 - ADC Input 2  
IRQC - Default external interrupt source C  
TIM1C2 - Timer 1 channel 2 input/output |
| 29                                          | 42                        | PB6  | Digital I/O  
ADC1 - ADC Input 1  
IRQB - External interrupt source B  
TIM1C1 - Timer 1 channel 1 input/output |
| 30                                          | 43                        | PB5  | Digital I/O  
ADC0 - ADC Input 0  
TIM2CLK - Timer 2 external clock input  
TIM1MSK - Timer 1 external clock mask input |
| 32                                          | NC                        | RF Out | Castellation Pin for external Antenna |

**Note:** PC5 Applies only to the ZICM357SP0; PC5 is a NC on the ZICM357SP2.
MODULE DIMENSIONS

MeshConnect EM357 Mini Modules.

Note: All dimensions are +/- 0.005" (0.12mm) unless otherwise specified.
MODULE LAND FOOTPRINT

Dimensions are shown in inches, with millimeter conversions in brackets.

**Note:** Refer to the Antenna Section in this document for layout recommendations which will yield optimal antenna performance.
PROCESSING

**Recommended Reflow Profile**

<table>
<thead>
<tr>
<th>Parameter Values</th>
<th>Values</th>
</tr>
</thead>
<tbody>
<tr>
<td>Ramp up rate (from $T_{soakmax}$ to $T_{peak}$)</td>
<td>3º/sec max</td>
</tr>
<tr>
<td>Minimum Soak Temperature</td>
<td>150ºC</td>
</tr>
<tr>
<td>Maximum Soak Temperature</td>
<td>200ºC</td>
</tr>
<tr>
<td>Soak Time</td>
<td>60-120 sec</td>
</tr>
<tr>
<td>$T_{Liquidus}$</td>
<td>217ºC</td>
</tr>
<tr>
<td>Time above $T_{Liquidus}$</td>
<td>60-150 sec</td>
</tr>
<tr>
<td>$T_{peak}$</td>
<td>250ºC</td>
</tr>
<tr>
<td>Time within 5º of $T_{peak}$</td>
<td>20-30 sec</td>
</tr>
<tr>
<td>Time from 25º to $T_{peak}$</td>
<td>8 min max</td>
</tr>
<tr>
<td>Ramp down rate</td>
<td>6ºC/sec max</td>
</tr>
</tbody>
</table>

**Pb-Free Solder Paste**

Use of “No Clean” soldering paste is strongly recommended, as it does not require cleaning after the soldering process.

*Note: The quality of solder joints on the castellations ("half vias") where they contact the host board should meet the appropriate IPC Specification. See the Castellated Terminations Section in the latest IPC-A-610 Acceptability of Electronic Assemblies document.*

**Cleaning**

In general, cleaning the populated module is strongly discouraged. Residuals under the module cannot be easily removed with any cleaning process.

- Cleaning with water can lead to capillary effects where water is absorbed into the gap between the host board and the module. The combination of soldering flux residuals and encapsulated water could lead to short circuits between neighboring pads. Water could also damage any stickers or labels.
- Cleaning with alcohol or a similar organic solvent will likely flood soldering flux residuals into the two housings, which is not accessible for post-washing inspection. The solvent could also damage any stickers or labels.
- Ultrasonic cleaning could damage the module permanently.

The best approach is to consider using a “No Clean” solder paste and eliminate the post-soldering cleaning step.

**Optical Inspection**

After soldering the module to the host board, consider optical inspection to check the following:

- Proper alignment and centering of the module over the pads
- Proper solder joints on all pads
- Excessive solder or contacts to neighboring pads or vias

**Repeating Reflow Soldering**

Only a single reflow soldering process is encouraged for host boards.

**Wave Soldering**

If a wave soldering process is required on the host boards due to the presence of leaded components, only a single wave soldering process is encouraged.

**Hand Soldering**

Hand soldering is possible. When using a soldering iron, follow IPC recommendations (reference document *IPC-7711*).
**Rework**
The MeshConnect Module can be unsoldered from the host board. Use of a hot air rework tool should be programmable and the solder joint and module should not exceed the maximum peak reflow temperature of 250°C.

**Caution**
If temperature ramps exceed the reflow temperature profile, module and component damage may occur due to thermal shock. Avoid overheating.

**Warning**
Never attempt a rework on the module itself (i.e., replacing individual components); such actions will terminate warranty coverage.

**Additional Grounding**
Attempts to improve the module or the system grounding by soldering braids, wires or cables onto the module RF shield cover is done at the customer's own risk. The ground pins at the module perimeter should be sufficient for optimum immunity to external RF interference.
AGENCY CERTIFICATIONS

The following Part Numbers are Certified as shown below:

<table>
<thead>
<tr>
<th>Part Number</th>
<th>Certifications</th>
<th>Antenna</th>
</tr>
</thead>
<tbody>
<tr>
<td>ZICM357SP0-1</td>
<td>FCC, IC, CE</td>
<td>PCB</td>
</tr>
<tr>
<td>ZICM357SP2-1</td>
<td>FCC, IC</td>
<td>PCB</td>
</tr>
<tr>
<td>ZICM357SP2-1C</td>
<td>FCC, IC</td>
<td>Nearson S181AH-2450S</td>
</tr>
</tbody>
</table>

FCC Compliance Statement Part 15.19, Section 7.15 of RSS-GEN

This device complies with Part 15 of the FCC Rules and with Industry Canada licence-exempt RSS Standards. Operation is subject to the following two conditions:

1. This device may not cause harmful interference, and  
2. This device must accept any interference received, including interference that may cause undesired operation.

Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes:

1. l'appareil ne doit pas produire de brouillage, et  
2. l'utilisateur de l'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

Warning (Part 15.21)

Changes or modifications not expressly approved by CEL could void the user's authority to operate the equipment.

20cm Separation Distance

To comply with FCC/IC RF exposure limits for general population/uncontrolled exposure, the antenna(s) used for this transmitter must be installed to provide a separation distance of at least 20cm from all persons and must not be co-located or operated in conjunction with any other antenna or transmitter.

OEM Responsibility to the FCC and IC Rules and Regulations

The MeshConnect Mini Module has been certified per FCC Part 15 Rules and to Industry Canada license-exempt RSS Standards for integration into products without further testing or certification. To fulfill the FCC and IC Certification requirements, the OEM of the MeshConnect Module must ensure that the information provided on the MeshConnect label is placed on the outside of the final product. The MeshConnect Mini Module is labeled with its own FCC ID Number and IC ID Number. If the FCC ID and the IC ID are not visible when the module is installed inside another device, then the outside of the device into which the module is installed must also display a label referring to the enclosed module. The exterior label can use wording such as the following:

"Contains Transmitter Module FCC ID: W7Z-ZICM357SP0" or "Contains FCC ID: W7Z-ZICM357SP0"  
"Contains Transmitter Module IC: 8254A-ZICM357SP0" or "Contains IC: 8254A-ZICM357SP0" 
or
"Contains Transmitter Module FCC ID: W7Z-ZICM357SP2" or "Contains FCC ID: W7Z-ZICM357SP2"  
"Contains Transmitter Module IC: 8254A-ZICM357SP2" or "Contains IC: 8254A-ZICM357SP2"

The OEM of the MeshConnect Mini Module may only use the approved antennas (PCB Trace Antenna and external antenna (part number: S181AH-2450S)) that have been certified with this module. The OEM of the MeshConnect Mini Module must test their final product configuration to comply with Unintentional Radiator Limits before declaring FCC Compliance per Part 15 of the FCC Rules.
IC Certification — Industry Canada Statement
The term "IC" before the certification/registration number only signifies that the Industry Canada technical specifications were met.

Certification IC — Déclaration d'Industrie Canada
Le terme "IC" devant le numéro de certification/d'enregistrement signifie seulement que les spécifications techniques Industrie Canada ont été respectées.

Section 14 of RSS-210
The installer of this radio equipment must ensure that the antenna is located or pointed such that it does not emit RF field in excess of Health Canada limits for the general population. Consult Safety Code 6, obtainable from Health Canada's website: http://www.hc-sc.gc.ca/ewh-semt/pubs/radiation/radio_guide-lignes_direct-eng.php

CE Certification — Europe
The MeshConnect ZICM35xSP0 Module has been tested and certified for use in the European Union.

OEM Responsibility to the European Union Compliance Rules
If the MeshConnect Module is to be incorporated into a product, the OEM must verify compliance of the final product to the European Harmonized EMC and Low-Voltage/Safety Standards. A Declaration of Conformity must be issued for each of these standards and kept on file as described in Annex II of the R&TTE Directive.

The manufacturer must maintain the user guide and adhere to the settings described in the manual for maintaining European Union Compliance. If any of the specifications are exceeded in the final product, the OEM is required to make a submission to the notified body for compliance testing.

OEM Labeling Requirements
The CE mark must be placed on the OEM product in a visible location. The CE mark shall consist of the initials CE with the following form:

- If the CE marking is reduced or enlarged, the proportions given in the CE graduated drawing (to the right) must be adhered to
- The CE mark must be a minimum of 5mm in height
- If the use of the module is subject to restrictions in the end application, the CE marking on the OEM product should also include the alert sign as shown in the image to the right
Software Compliance

The MeshConnect Mini Modules require software restrictions to meet agency certification requirements. These restrictions have been implemented in the sample application included with the Software Development Kit.

If a customer is not starting with the CEL Software Development Kit, they must implement the following output power restrictions to use the FCC, IC or CE Certifications:

<table>
<thead>
<tr>
<th>Certification</th>
<th>RF Channel</th>
<th>Valid TX Power Steps</th>
<th>Typical Max Output Power</th>
</tr>
</thead>
<tbody>
<tr>
<td>ZICM357SP0-1</td>
<td>11 - 25</td>
<td>-43 to 8</td>
<td>8 dBm</td>
</tr>
<tr>
<td></td>
<td>26</td>
<td>-43 to 0</td>
<td>1 dBm</td>
</tr>
<tr>
<td></td>
<td>ETSI</td>
<td>11 - 26</td>
<td>8 dBm</td>
</tr>
<tr>
<td>ZICM357SP2-1</td>
<td>11 - 24</td>
<td>-43 to -2</td>
<td>20 dBm</td>
</tr>
<tr>
<td></td>
<td>25</td>
<td>-43 to -6</td>
<td>17 dBm</td>
</tr>
<tr>
<td></td>
<td>26</td>
<td>-43 to -36</td>
<td>-3 dBm</td>
</tr>
<tr>
<td>ZICM357SP2-1C</td>
<td>11 - 24</td>
<td>-43 to -2</td>
<td>20 dBm</td>
</tr>
<tr>
<td></td>
<td>25</td>
<td>-43 to -12</td>
<td>9 dBm</td>
</tr>
<tr>
<td></td>
<td>26</td>
<td>-43 to -38</td>
<td>-5 dBm</td>
</tr>
</tbody>
</table>

Note: The ZICM357SP2, Power Mode 2 with Power Setting -2 is the maximum setting allowed for FCC Compliance. Operating in Power Mode 3 at higher power settings may damage the PA.
**SHIPMENT, HANDLING AND STORAGE**

**Shipment**
The MeshConnect Modules have two delivery options (see Ordering Information on page 3):
1. Trays (in bundles) of 330 units. Each tray contains 66 units
2. Tape and Reel for easy assembly in a manufacturing environment. The reel diameter is 12.992 inches (330mm) and contains 600 modules

**Tape and Reel Dimensions**
Measurements are in inches [mm]

```
0.957±0.004 [24.30±0.10]

0.079±0.004 [2.00±0.10]
0.014±0.002 [0.35±0.05]
0.169±0.004 [4.30±0.10]
0.945±0.004 [24.00±0.10]

0.669±0.004 [17.00±0.10]
```

**Handling**
The MeshConnect Modules are designed and packaged to be processed in an automated assembly line.

**Warning**
The MeshConnect Modules contain highly sensitive electronic circuitry. Handling without proper ESD protection may destroy or damage the module permanently.

**Warning**
The MeshConnect Modules are moisture-sensitive devices. Appropriate handling instructions and precautions are summarized in J-STD-033. Read carefully to prevent permanent damage due to moisture intake.

**Moisture Sensitivity Level (MSL)**
MSL 3, per J-STD-033

**Storage**
Storage/shelf life in sealed bags is 12 months at <40°C and <90% relative humidity.

**QUALITY**
CEL Modules offer the highest quality at competitive prices. Our modules are manufactured in compliance with the IPC-A-610 specification, Class II. Our modules go through JESD22 qualification processes which include high temperature operating life tests, mechanical shock, temperature cycling, humidity and reflow testing. CEL conducts RF and DC factory testing on 100% of all production parts.

CEL builds the quality into our products, giving our customers confidence when integrating our products into their systems.
### REFERENCES

<table>
<thead>
<tr>
<th>Reference Documents</th>
<th>Download</th>
</tr>
</thead>
<tbody>
<tr>
<td>120-035X-000 - Silicon Labs/Ember EM35x SoC Datasheet</td>
<td>Link</td>
</tr>
<tr>
<td>0011-02-17-00-000 - CEL EM35x Ember Mini Module Companion Kit Technical User Guide</td>
<td>Link</td>
</tr>
<tr>
<td>0011-00-16-11-000 - CEL ZICM357SP2-1C External Antenna Implementation</td>
<td>Link</td>
</tr>
</tbody>
</table>

### REVISION HISTORY

<table>
<thead>
<tr>
<th>Previous Versions</th>
<th>Changes to Current Version</th>
<th>Page(s)</th>
</tr>
</thead>
</table>
| 0011-00-07-00-000  
March 29, 2012 | Initial preliminary datasheet | N/A |
| 0011-00-07-00-000  
(Issue A) April 11, 2012 | Added FCC certification and shipping information; edited "Features" Section | 1, 13 |
| 0011-00-07-00-000  
(Issue B) May 4, 2012 | Updated Min/Multiple values | 1, 13 |
| 0011-00-07-00-000  
(Issue C) June 22, 2012 | Updated Software Compliance table | 13 |
| 0011-00-07-00-000  
(Issue D) July 31, 2012 | Updated land pattern; added note about operating in Boost Mode on SP2 | 9 |
| 0011-00-07-00-000  
(Issue E) February 28, 2013 | Removed “Preliminary” from first page | 1 |
| 0011-00-07-00-000  
(Issue F) July 19, 2013 | Updated Antenna Section, Software Compliance Section, Shipment Section | 4, 13, 14 |
| 0011-00-07-00-000  
(Issue G) July 31, 2013 | Updated Formatting | All |
| 0011-00-07-00-000  
(Issue H) October 18, 2013 | Updated Photo; updated Tape and Reel Packaging MOQ | 1, 3, 16 |
### Disclaimer

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### For More Information

For more information about CEL MeshConnect products and solutions, visit our website at: [www.cel.com/MeshConnect](http://www.cel.com/MeshConnect).

### Technical Assistance

For Technical Assistance, visit [www.cel.com/MeshConnectHelp](http://www.cel.com/MeshConnectHelp).